

from the first surface of the flat carrier and a circuit 5. The adhesive closure elements comprise hooks, mushroom-shaped members or loops. Circuit 5 is directly on the second surface of the flat carrier, and includes at least an electrical component or an electronic component.

By forming the adhesive closure part in this manner, the adhesive closure part is provided with increased functionality in a manner which is simple and compact to manufacture and use. This advantage is particularly provided by the circuit being directly on the flat carrier surface opposite the closure elements. Such arrangement is not disclosed or rendered obvious by any of the cited patents.

Claims 15-20 and 29-34 stand rejected under 35 U.S.C. §102 as being anticipated by newly cited U.S. Patent No. 4,429,348 to Dean. The Dean patent is cited as disclosing a flat carrier 16 having a first surface with hooks, mushroom-shaped members or loops and a circuit directly on a second surface of the flat carrier with the circuit having at least one electrical component 20 (apparently column 2, lines 5-15). The features of the dependent claims 16-20 and 29-34 are also alleged to be disclosed in the Dean patent.

Claims 21, 27 and 28 stand rejected under 35 U.S.C. §103 as being unpatentable over the Dean patent. In support of the rejection, official notice is taken of and it is alleged that it would be obvious to provide sensors and an electronic storage device in the Dean circuit.

Claims 22-26 stand rejected under 35 U.S.C. §103 as being unpatentable over the Dean patent in view of the previously cited U.S. Patent No. 6,173,899 to Rozin. The Rozin patent is cited for disclosing an integrated semi-conductor component that is allegedly obvious to include in the Dean circuit.

The pending claims, particularly claim 15, are patentably distinguishable over the Dean patent and the other cited patents since the Dean patent does not disclose a circuit directly on a second surface of the flat carrier where its opposite surface has adhesive closing elements. Specifically, the Dean patent discloses a circuit board 16 having printed circuitry on its rear surface 32 as illustrated in Fig. 2, which circuitry includes conductive paths 34, 36 and 38. A hook sheet 40, which is separated from the circuit board 16, is affixed by adhesive, tape or mechanical fasteners to the back face of circuit board 16 with the hook face of hook sheet 40 facing away from the circuit board 16 (column 2, lines 45-55). Thus, the Dean structure involves separate carriers for the circuit (i.e., circuit board 16) and for the adhesive closure elements (i.e., hook sheet 40) such that the circuit is not directly on the surface of the flat carrier opposite the adhesive closure elements as required in claim 15. Even if the flat carrier of the Dean patent is interpreted to be a combination of circuit board 16 and hook sheet 40, the circuit provided by conductive paths 34, 36 and 38 on the rear surface 32 of circuit board 16 would not be on the opposite surface of the combination as would be required to meet the language of claim 15, but would be on an inside surface.

Accordingly, claim 15 is patentably distinguishable over the Dean patent. None of the other cited patents cure these deficiencies in the Dean patent.

Claims 16-34, being dependent upon claim 15, are also allowable for the above reasons. Moreover, these dependent claims recite additional features further distinguishing them over the cited patents.

Claim 16 is further distinguishable by another electric or electronic component located in or directly on the flat carrier. Since none of the electrical or electronic components of the Dean

patent are in or directly on hook sheet 40, the Dean patent does not disclose or render obvious this feature.

Claim 17 is further distinguishable by another electrical or electronic component integrated into the flat carrier. No such component is in the Dean hook sheet as would be necessary to provide this feature.

Claim 18 is further distinguishable by the electrical or electronic component comprising an application of thick and thin film technology. Such structural limitation is not disclosed in the Dean patent.

Claim 19 is further distinguishable by the lamination of the electrical or electronic component onto the flat carrier. Nothing is laminated on Dean hook sheet 40.

Claim 20 is further distinguishable by the circuit comprising conductor strips that are on the flat carrier. The Dean patent does not disclose conductor strips directly on hook sheet 40.

Claim 21 is further distinguishable by the circuit comprising electrical or electronic sensors that are directly on the flat carrier. Relative to this feature, official notice is taken. Such taking of official notice is challenged such that the citation of evidence demonstrating the obviousness of this feature is now required. M.P.E.P. §2144.03 C.

Claim 22 is further distinguishable by the circuit comprising an integrated semiconductor component that is directly on the flat carrier. As noted above, such feature is not disclosed or rendered obvious by the Dean patent, and is not rendered obvious by the Rozin patent since the Rozin patent does not involve a flat carrier as claimed.

Claim 23- 26 are further distinguishable by the data memory (claim 23), the data readable without contact (claim 24), the data storable without contact (claim 25) and the coil where the

semiconductor component and coil are directly on the flat carrier (claim 26). Such structure is not taught by the Dean patent, for the reasons noted above. The Rozin patent does not disclose a flat carrier with adhesive closure elements on one surface and a circuit on another opposite surface, and thus, does not cure the deficiencies in the Dean patent.

Claims 27 and 28 are further distinguishable by the energy storage device (claim 27), which device is an application of thin or thick film technology (claim 28). Such devices are not disclosed or rendered obvious by the Dean patent since none are directly on a flat carrier with adhesive closure elements on its opposite side. Also relative to this feature, official notice is taken. Such taking of official notice is challenged such that the citation of evidence demonstrating the obviousness of this feature is now required. M.P.E.P. §2144.03 C.

Claim 29 is further distinguishable by the particular plastic materials, within the overall claimed combination.

Claim 30 is further distinguishable by the printed conductors directly on the flat carrier connected to an electrical component. No such direct connection is disclosed or rendered obvious by the Dean patent.

Claim 31 is further distinguishable by the circuit comprising printed electrical conductors directly on the flat carrier connected to an electrical component integrated in the flat carrier. Such structure is not provided by the Dean patent.

Claim 32 is further distinguishable by the circuit comprising printed electrical conductors directly on the flat carrier connected to and extending from an electronic component laminated directly on the flat carrier and connected to the printed conductors. No such printed conductors

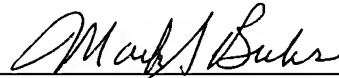
connected to a laminated electrical component are disclosed in or rendered obvious by the Dean patent.

Claim 33 is further distinguishable by the electrical conductors directly on the flat carrier having adjacent ends abutting one another which are movable between abutting and separated positions. No such arrangement is disclosed or rendered obvious by the Dean patent.

Claim 34 is further distinguishable by the flat carrier being flexible and insulating. Such flexibility and insulation are inherent in the Dean circuit board 16.

In view of the foregoing, claims 15-34 are allowable. Prompt and favorable action is solicited.

Respectfully submitted,



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